"RESPONSE UNDER 37 CFR 1.116-EXPEDITED PROCEDURE EXAMINING

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RESPONSE UNDER 37 C.F.R. §1.116 -**EXPEDITED PROCEDURE EXAMINING GROUP 2814**

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF

: EXAMINER: CAO, P. X.

SERIAL NO: 09/612,298

TATSUYA KUNIKIYO

FILED: JULY 7, 2000

: GROUP ART UNIT: 2814

FOR: SEMICONDUCTOR DEVICE

AMENDMENT UNDER 37 C.F.R. § 1.116

ASSISTANT COMMISSIONER FOR PATENTS WASHINGTON, D.C. 20231

SIR:

In response to the Office Action dated July 1, 2002, please amend the above-identified application as follows:

IN THE CLAIMS

Please amend Claims 1 and 7 as shown in clean form below. A marked-up copy of

the amended claim is attached.

1. (Amended) A semiconductor device comprising:

a semiconductor substrate having a main surface along which a semiconductor

element is formed;

interlayer insulating films formed on said main surface;

TECHNOLOGY CENTER 2800